

# CERTIFICATE OF INSPECTION & TEST (EN 10204 3.1)

**ST** ST&H CORPORATION  
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Certificate No. MES9300-06/09 Date : MAY. 09. 2016  
 Customer PLESA ANAHUAC Y CIAS., S.A. DE C.V.  
 Contract No. 23308  
 Spec. For Material ASTM A105N-14,ASME SA105N-15,NACE MR0175/ISO15156-1:2015  
 Heat Treatment 930°C NORMALIZED & A.C

Certified to ISO9001:2008, ISO14001:2004,PED97/23/EC by LRQA

Dimensional inspection ASME B16.5 - 2013

ITEM / SIZE	Q'ty	Heat No./ Batch No.	Size of Test Specimen		Tension Test				Hardness Test (HB)	Charpy Impact Test (10X10mm Specimen Size)						
			D	GL	Y.S MPa	T.S MPa	E.L %	R.A %		187	Indiv.	Ave.	Notch	Temp.		
			mm	mm					Max						Min	250
BA600WR8012 600LBS WN RF S80 12"	10	202624L	12.5	50.0			318	512	34	66	163	183				
BA600WRSTD10 600LBS WN RF STD 10"	10	202624L	12.5	50.0			318	512	34	66	163	183				
BA150SR20 150LBS SO RF 20"	5	202624M	12.5	50.0			318	512	34	66	163	183				
BA150SR18 150LBS SO RF 18"	10	202624M	12.5	50.0			318	512	34	66	163	183				
BA150SR16 150LBS SO RF 16"	10	202624M	12.5	50.0			318	512	34	66	163	183				
BLANK		BLANK					BLANK				BLANK					

Heat No./ Batch No.	Max Min	Chemical Composition (%)										CE	NDE				
		C	Si	Mn	P	S	Ni	Cr	Mo	Cu	V		UT	MT	PT		
		0.350	0.350	1.050	0.035	0.040	0.400	0.300	0.120	0.400	0.080						
202624L	H	0.198	0.231	0.890	0.017	0.020	0.015	0.132	0.002	0.009	0.002						0.375
	P	0.168	0.232	0.870	0.019	0.014	0.014	0.114	0.002	0.010	0.003						0.338
202624M	H	0.198	0.231	0.890	0.017	0.020	0.015	0.132	0.002	0.009	0.002						0.375
	P	0.168	0.232	0.870	0.019	0.014	0.014	0.114	0.002	0.010	0.003						0.338
		BLANK															

REMARK \* H : Heat Analysis P : Product Analysis

We hereby certify that the material herein has been made and tested in accordance with the above specification and also with the requirements called for by the above order.

Witnessed by / H. J. LEE

Manager of Q.A Dept. / E. S. PARK

*Handwritten signature: H. J. LEE*

